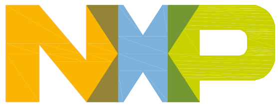

PIN 1 INDEX AREA

9

A

0.1 C

2X

DETAIL G

M

9

B

0.1 C

2X

M

6.15
5.85

0.1 C A B

49

64

DETAIL M
PIN 1 INDEX

48

1

EXPOSED DIE ATTACH PAD

0.25

6.15
5.85

0.1 C A B

60X 0.5

33

16

DETAIL N

32

17

64X 0.30
0.18

64X 0.55
0.45

0.1 Ⓜ C A B
0.05 Ⓜ C

VIEW M–M

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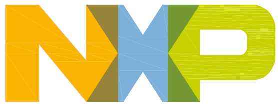
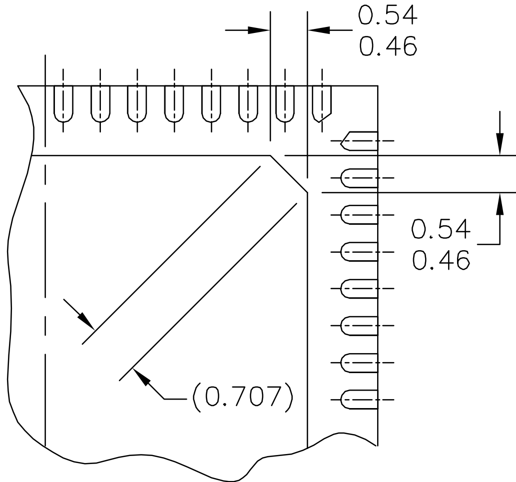
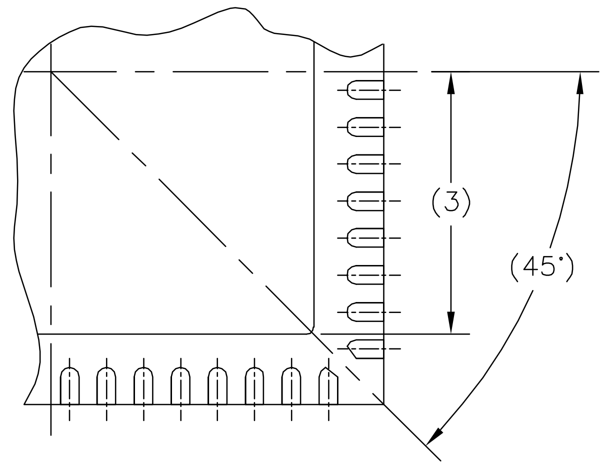
TITLE: THERMALLY ENHANCED QUAD FLAT NON–LEADED PACKAGE (QFN) 64 TERMINAL, 0.5 PITCH (9 X 9 X 1)	DOCUMENT NO: 98ASA10690D	REV: A
	STANDARD: JEDEC MO–220 VMMD–3	
	SOT804–7	10 MAR 2016

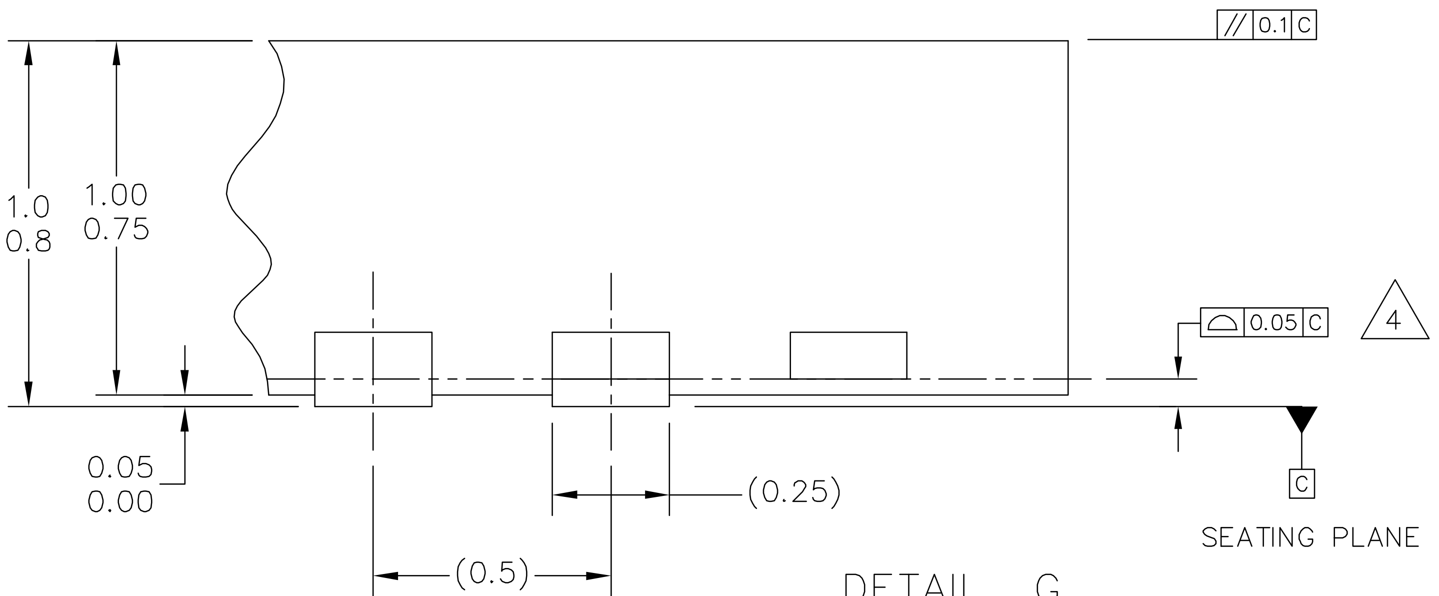






DETAIL M
PREFERRED PIN1 BACKSIDE IDENTIFIER

DETAIL N
PREFERRED CORNER CONFIGURATION



DETAIL G
VIEW ROTATED 90° CW

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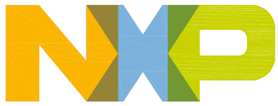
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 64 TERMINAL, 0.5 PITCH (9 X 9 X 1)	DOCUMENT NO: 98ASA10690D	REV: A
	STANDARD: JEDEC MO-220 VMMD-3	
	SOT804-7	10 MAR 2016



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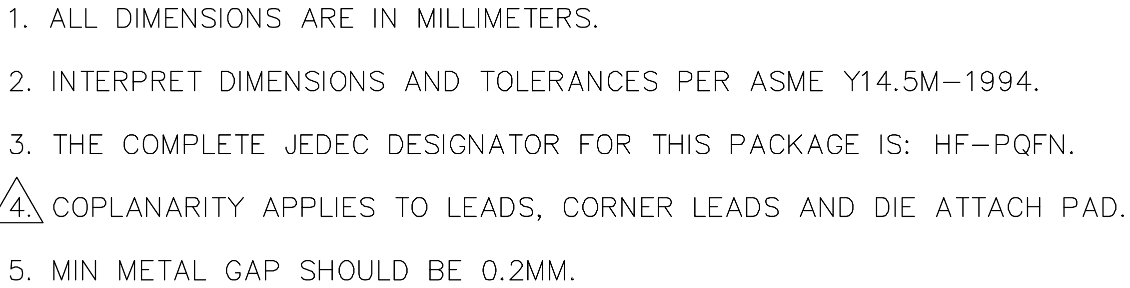

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF–PQFN.
4. COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2MM.

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

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DOCUMENT NO: 98ASA10690D REV: A

STANDARD: JEDEC MO–220 VMMD–3

SOT804–7 10 MAR 2016